



PRODUCT DATA SHEET



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Datasheet



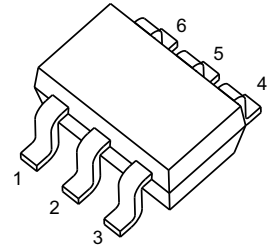
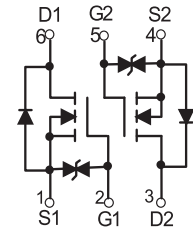
Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
20V	380mΩ@4.5V	0.75A
	450mΩ@2.5V	
	800mΩ@1.8V	


SOT-363

FEATURE

- Lead Free Product is Acquired
- Surface Mount Package
- N-Channel Switch with Low $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive
Equivalent to Two BSD840N

APPLICATION

- Load/Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	20	V
Typical Gate-source voltage	V_{GS}	±12	V
Continuous drain current ($t \leq 10\text{s}$)	I_D	0.75	A
Power dissipation*	P_D	0.15	W
Thermal resistance from junction to ambient	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55~ +150	$^\circ\text{C}$

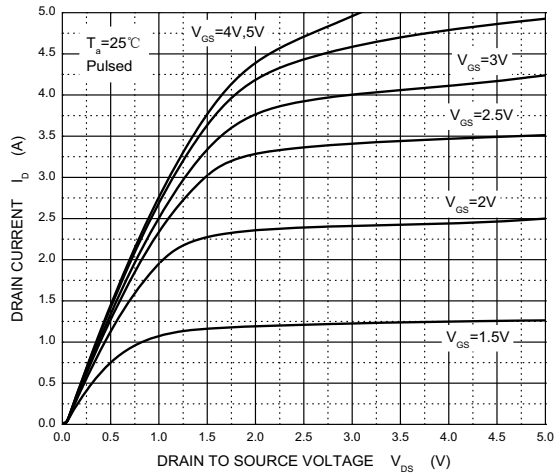
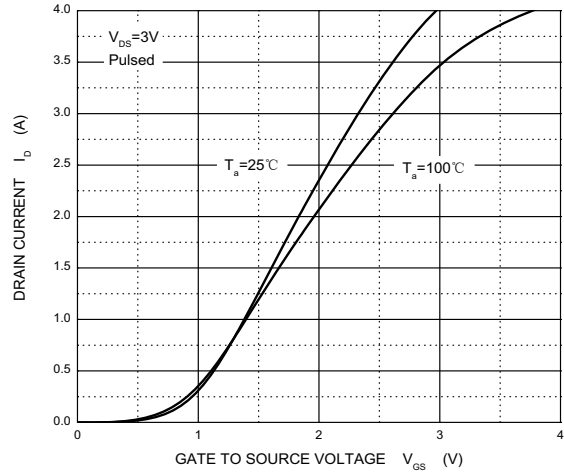
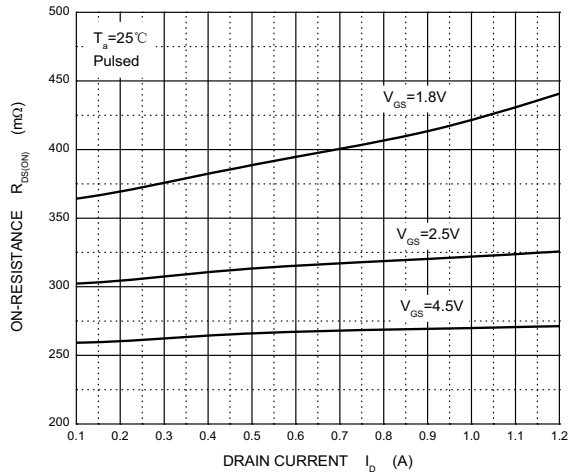
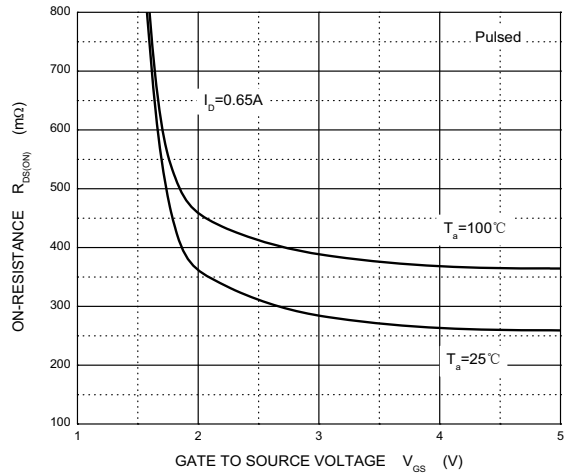
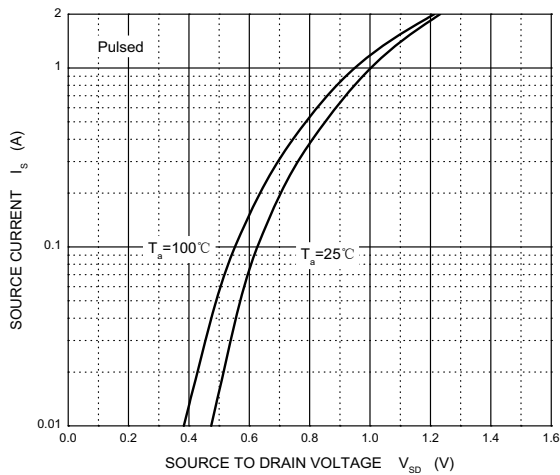
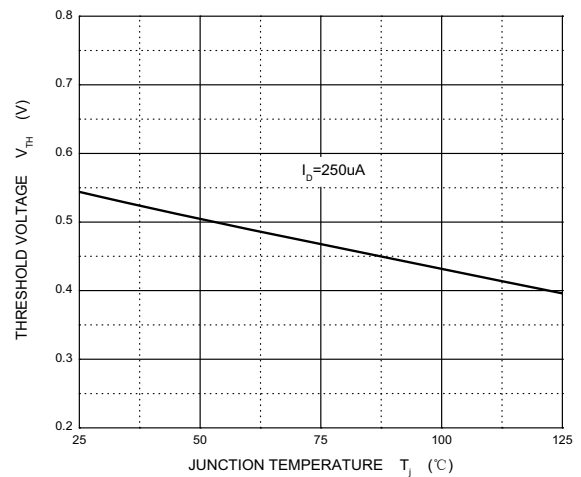
* Repetitive rating : Pulse width limited by junction temperature.

MOSFET ELECTRICAL CHARACTERISTICS $T_a=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$			± 20	μA
Gate threshold voltage (note 1)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.35	0.54	1.1	V
Drain-source on-resistance (note 1)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 0.65A$		270	380	$m\Omega$
		$V_{GS} = 2.5V, I_D = 0.55A$		320	450	$m\Omega$
		$V_{GS} = 1.8V, I_D = 0.45A$		390	800	$m\Omega$
Forward transconductance (note 1)	g_{FS}	$V_{DS} = 10V, I_D = 0.8A$		1.6		S
Diode forward voltage (note 1)	V_{SD}	$I_S = 0.15A, V_{GS} = 0V$			1.2	V
DYNAMIC PARAMETERS (note 2)						
Input Capacitance	C_{iss}	$V_{DS} = 16V, V_{GS} = 0V, f = 1MHz$		79	120	pF
Output Capacitance	C_{oss}			13	20	pF
Reverse Transfer Capacitance	C_{rss}			9	15	pF
SWITCHING PARAMETERS (note 2)						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_D = 0.5A, R_{GEN} = 10\Omega$		6.7		ns
Turn-on rise time	t_r			4.8		ns
Turn-off delay time	$t_{d(off)}$			17.3		ns
Turn-off fall time	t_f			7.4		ns
Total Gate Charge	Q_g	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 0.25A$		750		pC
Gate-Source Charge	Q_{gs}			75		pC
Gate-Drain Charge	Q_{gd}			225		pC

Notes :

1. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 0.5\%$.
2. Guaranteed by design, not subject to production testing.

Output Characteristics

Transfer Characteristics

 $R_{DS(ON)}$ — I_D

 $R_{DS(ON)}$ — V_{GS}

 I_S — V_{SD}

Threshold Voltage


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